

28 October 2003

09/868,577

L Number	Hits	Search Text	DB	Time stamp
-	1571	204/\$.ccls. and (wafer or semiconductor) and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 08:45
-	2570	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 08:45
-	1487	204/224r,224m.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 08:46
-	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 08:46
-	218	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)) and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:30
-	60	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and sponge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:18
-	2	6176992.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:25
-	14	("3595089" "4610772" "5024735" "5171412" "5429733" "5558568" "5692947" "5755859" "5807165" "5833820" "5863412" "5930669" "5933753" "6004880").PN.	USPAT	2003/10/27 09:26
-	2	6228233.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:33
-	2	4807973.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:33

	23	(204/\$.ccls. or 205/\$.ccls.) and datta.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:33
	3838	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:53
	313	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (temperature with (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:54
	67	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (temperature near2 (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:03
	10	3859196.URPN.	USPAT	2003/10/27 11:01
	30	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and ((temperature near2 control\$5) with (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:13
	2	("5507923" "6017437").PN.	USPAT	2003/10/27 11:06
	25	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and ((coolant or (cooling adj (fluid or liquid))) with (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:19
	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:20
	375	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)) and (coolant or (cooling fluid) or heat or heating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
	176	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling fluid) or heat or heating) with (anode or cahode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
	93	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling fluid) or heat or heating) near3 (anode or cahode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:21

	9	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling adj fluid) or heat or heating) near3 (anode or cahode or electrode))	sUSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:21
	197	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc 204/224r,224m.ccls.) and (wafer or semiconductor)) and (coolant or (cooling adj fluid) or heat or heating)	sUSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
	32	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling adj fluid) or heat or heating) with (anode or cahode or electrode))	sUSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
	2	("5507923" "6017437").PN.	USPAT	2003/10/27 11:27
	0	868577.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:42
	22	(US-6077412-\$ or US-6017437-\$ or US-5951833-\$ or US-5567300-\$ or US-5776330-\$ or US-6176992-\$ or US-6228233-\$ or US-6251235-\$ or US-6258240-\$ or US-6261433-\$ or US-6270647-\$ or US-6328872-\$ or US-6334937-\$ or US-6103096-\$ or US-5284554-\$ or US-3859196-\$ or US-6398926-\$ or US-5228966-\$ or US-5198083-\$ or US-3894925-\$ or US-3637468-\$).did. or (US-20020056647-\$).did.	USPAT; US-PGPUB	2003/10/27 11:50
	8	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$ or US-5567300-\$ or US-5776330-\$ or US-6176992-\$ or US-6228233-\$ or US-6251235-\$ or US-6258240-\$ or US-6261433-\$ or US-6270647-\$ or US-6328872-\$ or US-6334937-\$ or US-6103096-\$ or US-5284554-\$ or US-3859196-\$ or US-6398926-\$ or US-5228966-\$ or US-5198083-\$ or US-3894925-\$ or US-3637468-\$).did. or (US-20020056647-\$).did.) and ((electrolyte or solution or fluid) with (temperature or cool\$4 or heat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:51
	7	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$ or US-5567300-\$ or US-5776330-\$ or US-6176992-\$ or US-6228233-\$ or US-6251235-\$ or US-6258240-\$ or US-6261433-\$ or US-6270647-\$ or US-6328872-\$ or US-6334937-\$ or US-6103096-\$ or US-5284554-\$ or US-3859196-\$ or US-6398926-\$ or US-5228966-\$ or US-5198083-\$ or US-3894925-\$ or US-3637468-\$).did. or (US-20020056647-\$).did.) and (dc or (direct adj current))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 12:32